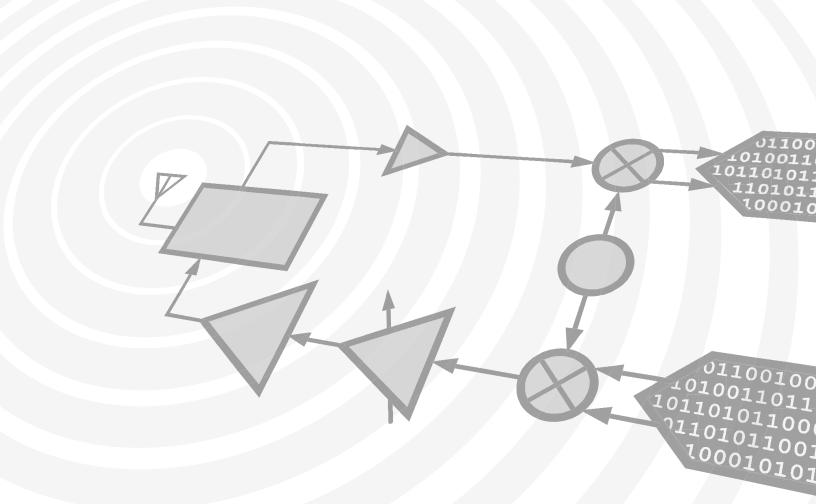




# Analog Devices Welcomes Hittite Microwave Corporation







### HMC540SLP3E

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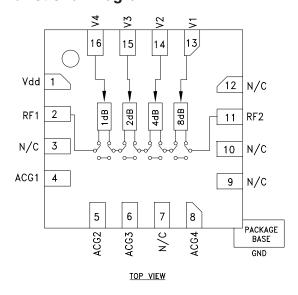
### 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### Typical Applications

The HMC540SLP3E is ideal for both RF and IF applications:

- Cellular Infrastructure
- Wireless Infrastructure
- Microwave Radio & VSAT
- Test Equipment and Sensors

#### **Functional Diagram**



#### **Features**

1 dB LSB Steps to 15 dB ± 0.2 dB Typical Step Error Low Insertion Loss: =< 1 dB

High IP3: +56 dBm

Single Control Line Per Bit

TTL/CMOS Compatible Control

Single +3.3/+5V Supply

3x3 mm SMT Package

ESD rating: Class 2 (2kV HBM)

Drop-in Replacement for HMC540LP3E

#### **General Description**

The HMC540SLP3E is a broadband 4-bit Silicon IC digital attenuator in a low cost leadless surface mount package. This single positive control line per bit digital attenuator utilizes off chip AC ground capacitors for near DC operation, making it suitable for a wide variety of RF and IF applications. Covering 0.1 to 8 GHz, the insertion loss is less than 1 dB typical. The attenuator bit values are 1 (LSB), 2, 4 and 8 dB for a total attenuation of 15 dB. Attenuation accuracy is excellent at  $\pm$  0.2 dB typical step error. The attenuator also features a IIP3 of +56dBm. Four TTL/CMOS control inputs are used to select each attenuation state. It can operate with a single Vdd ranging from +3.3V to 5V.

#### Electrical Specifications,

 $T_A = +25^{\circ}$  C, With Vdd = +5V & VctI = 0/+5V (Unless Otherwise Noted)

Parameter	Frequency (GHz)	Min.	Тур.	Max.	Units
Insertion Loss	0.1 - 2.0 GHz 2.0 - 3.0 GHz 3.0 - 4.0 GHz 4.0 -5.5 GHz 5.5 - 8.0 GHz		0.7 0.8 0.8 1.0 1.7	1.1 1.3 1.6 2.6 3.0	dB dB dB dB
Attenuation Range	0.1 - 8 GHz		15		dB
Return Loss (RF1 & RF2, All Atten. States)	0.1 - 3.5 GHz 3.5 - 5.5 GHz 5.5 - 8 GHz		22 17 12		dB dB dB
Attenuation Accuracy: (Referenced to Insertion Loss)  All St.	0.1 - 1.0 GHz 1.0 - 4.0 GHz 4.0 - 5.0 GHz 5.0 - 5.5 GHz 5.5 GHz - 8 GHz	1.0 - 4.0 GHz		dB dB dB dB	



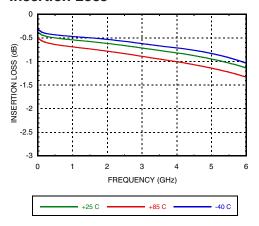
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### 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

Parameter		Frequency (GHz)	Min.	Тур.	Max.	Units
Input Power for 0.1 dB Compression		0.1 - 8 GHz		31		dBm
Input Third Order Intercept Point (Two-Tone Input Power= 12 dBm Each Tone)	REF - 4 dB States 5 - 15 dB States	0.1 - 8 GHz		57 55		dBm
Switching Characteristics	DC -8 GHz					
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)		DC -8 GHZ		45 129		ns ns

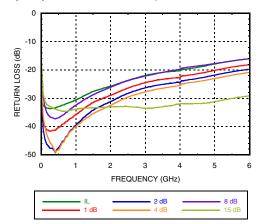
#### Frequency Response Plots up to 6 GHz

#### **Insertion Loss**



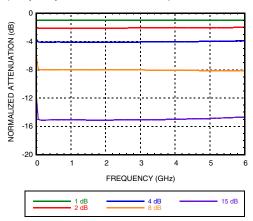
#### Return Loss RF1, RF2

(Only Major States are Shown)

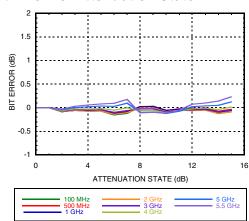


#### **Normalized Attenuation**

(Only Major States are Shown)



#### Bit Error vs. Attenuation State





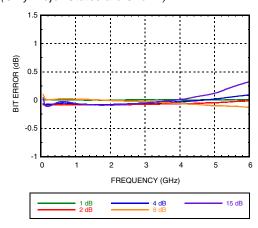
### HMC540SLP3E

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# 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

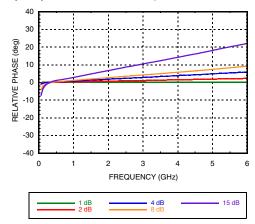
#### Bit Error vs. Frequency

(Only Major States are Shown)

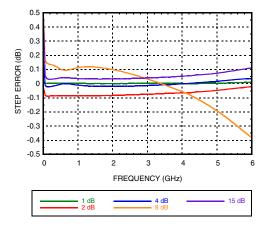


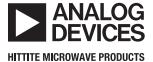
#### Relative Phase vs. Frequency

(Only Major States are Shown)



#### Step Error vs Frequency (Major States)

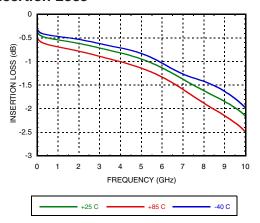




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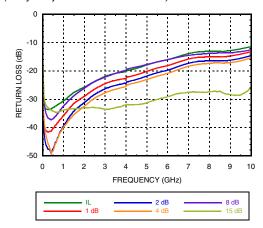
### 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

### Frequency Response Plots up to 10 GHz Insertion Loss



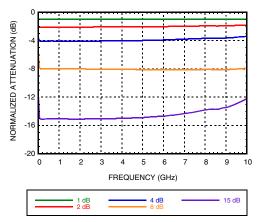
#### Return Loss RF1, RF2

(Only Major States are Shown)

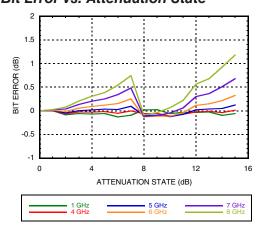


#### **Normalized Attenuation**

(Only Major States are Shown)

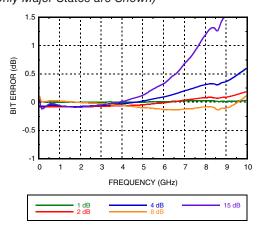


#### Bit Error vs. Attenuation State



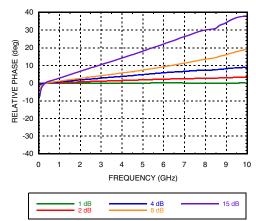
#### Bit Error vs. Frequency

(Only Major States are Shown)



#### Relative Phase vs. Frequency

(Only Major States are Shown)



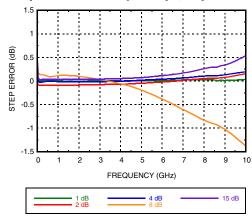


### HMC540SLP3E

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# 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### Step Error vs Frequency (Major States)

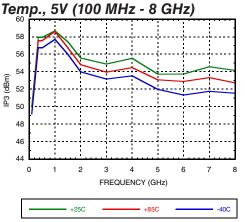




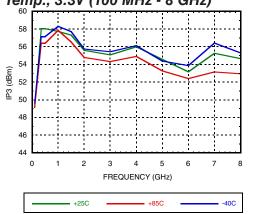
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### 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

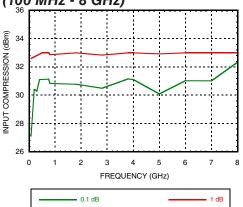
Power Handling up to 8 GHz Input Third Order Intercept Point over



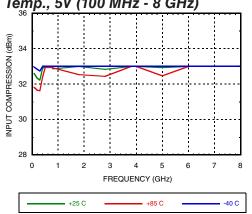
Input Third Order Intercept Point over Temp., 3.3V (100 MHz - 8 GHz)



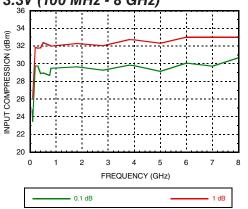
0.1 and 1 dB Input Compression Point, 5V (100 MHz - 8 GHz)



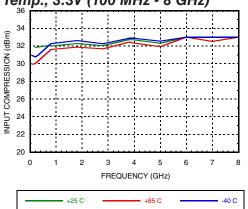
1 dB Input Compression Point, Over Temp., 5V (100 MHz - 8 GHz)



0.1 and 1 dB Input Compression Point, 3.3V (100 MHz - 8 GHz)



1 dB Input Compression Point, Over Temp., 3.3V (100 MHz - 8 GHz)





# 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### **Absolute Maximum Ratings**

RF Input Power at 85 °C	+27 dBm
RF Input Power at 105 °C	+25 dBm
Bias Voltage (Vdd)	-0.3V to 5.4V
Control Voltage Range (V1 to V4)	-0.3V to Vdd +.5V
Channel Temperature	140 °C
Thermal Resistance (at maximum power dissipation)	110 °C/W
ESD Sensitivity (HBM)	Class 2
Storage Temperature	-65 to +150 °C

#### **Recommended Operation Ratings**

RF Input Power at 85 °C	+24 dBm
RF Input Power at 105 °C	+23 dBm
Bias Voltage (Vdd)	3V to 5.4V
Control Voltage Range (V1 to V4)	0 to Vdd
Operating Temperature	-40 to +105 °C



#### Bias Voltage & Current

Vdd (V)	ldd (Typ.) (mA)
+3.3	0.14
+5.0	0.17

#### **Control Voltage**

State	Vdd = +3.3V	Vdd = +5V
Low	0 to 0.5V @ < 1 uA	0 to +0.8V @ < 1 uA
High	2 to 3.3V @ 25 uA	2 to 5V @ 35 uA

#### **Truth Table**

Control Voltage Input				Attenuation
V1 8 dB	V2 4 dB	V3 2 dB	V4 1 dB	State RF1 - RF2
High	High	High	High	Reference I.L.
High	High	High	Low	1 dB
High	High	Low	High	2 dB
High	Low	High	High	4 dB
Low	High	High	High	8 dB
Low	Low	Low	Low	15 dB

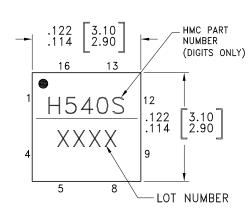
Any combination of the above states will provide an attenuation approximately equal to  $\,$  the sum of the bits selected.

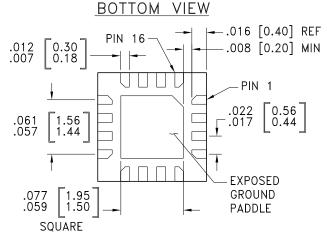


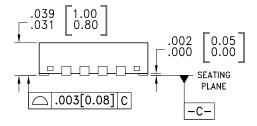
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## 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### **Outline Drawing**







#### NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

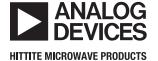
#### Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC540SLP3E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL3 <sup>[2]</sup>	H540S XXXX

<sup>[1]</sup> Max peak reflow temperature of 235 °C

<sup>[2]</sup> Max peak reflow temperature of 260  $^{\circ}\text{C}$ 

<sup>[3] 4-</sup>Digit lot number XXXX



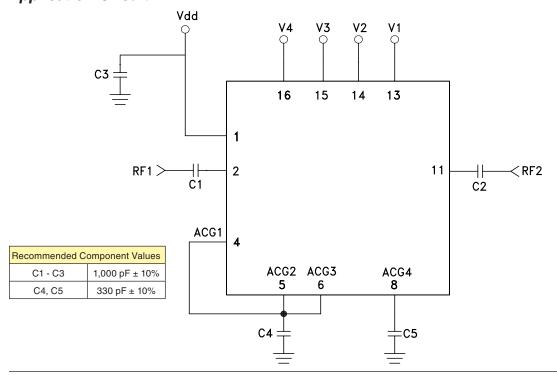
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# 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### **Pin Descriptions**

Pin Number	Function	Description	Interface Schematic
1	Vdd	Supply Voltage.	
2, 11	RF1, RF2	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required. Select value based on lowest frequency of operation.	RF1 ESD ESD
3, 7, 9, 10, 12	N/C	These pins should be connected to PCB RF ground to maximize performance.	
4 - 6, 8	ACG1 - ACG4	External capacitor to ground is required. Select value for lowest frequency of operation. Place capacitor as close to pins as possible.	
13 - 16	V1 - V4	See truth table and control voltage table.	(V1 <u>/Vs</u> ) 500
	GND	Package bottom has an exposed metal paddle that must be connected to RF/DC Ground.	GND =

#### **Application Circuit**

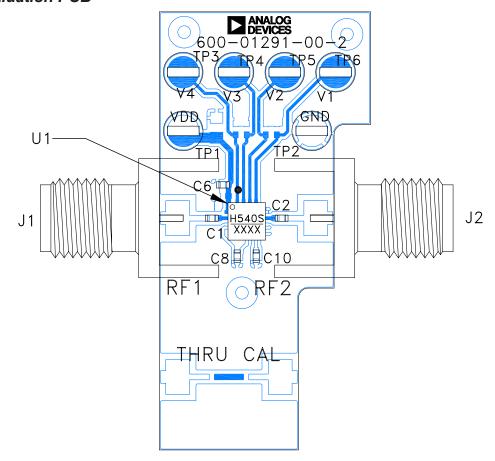




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### 1 dB LSB SILICON MMIC 4-BIT DIGITAL POSITIVE CONTROL ATTENUATOR, 0.1 - 8 GHz

#### **Evaluation PCB**



#### List of Materials for Evaluation PCB EV1HMC540SLP3[1]

Item	Description
J1, J2	PCB Mount SMA Connector
TP1 - TP6	Thru Hole Mount Test Point
C1, C2, C6	1000 pF Capacitor, 0402 Pkg.
C8, C10	330 pF Capacitor, 0402 Pkg.
U1	HMC540SLP3E Digital Attenuator
PCB [2]	600-01291-00 Evaluation PCB

<sup>[1]</sup> Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Analog Devices upon request.

<sup>[2]</sup> Circuit Board Material: Rogers 4350

### **Mouser Electronics**

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HMC540SLP3E EV1HMC540SLP3